### 505314013 02/05/2019

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5360794

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

### **CONVEYING PARTY DATA**

Name	Execution Date
MACDERMID OFFSHORE SOLUTIONS, LLC	01/31/2019

### **RECEIVING PARTY DATA**

Name:	BARCLAYS BANK PLC, AS COLLATERAL AGENT
Street Address:	745 SEVENTH AVENUE
Internal Address:	27TH FLOOR
City:	NEW YORK
State/Country:	NEW YORK
Postal Code:	10019

### **PROPERTY NUMBERS Total: 8**

Property Type	Number
Application Number:	14017786
Application Number:	13044613
Application Number:	14157928
Application Number:	12173284
Application Number:	12549579
Application Number:	12469337
Application Number:	14041669
Application Number:	13475030

### **CORRESPONDENCE DATA**

**Fax Number:** (212)751-4864

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 212-906-1216

Email: angela.amaru@lw.com

Correspondent Name: LATHAM & WATKINS LLP C/O ANGELA M. AMARU

Address Line 1: 885 THIRD AVENUE

Address Line 4: NEW YORK, NEW YORK 10022

ATTORNEY DOCKET NUMBER: 030786-0725

NAME OF SUBMITTER: ANGELA M. AMARU

PATENT 505314013 REEL: 049823 FRAME: 0055

**SIGNATURE:** /s/ Angela M. Amaru **DATE SIGNED:** 02/05/2019 **Total Attachments: 39** source=PSP - Patent Security Agreement Executed#page1.tif source=PSP - Patent Security Agreement Executed#page2.tif source=PSP - Patent Security Agreement Executed#page3.tif source=PSP - Patent Security Agreement Executed#page4.tif source=PSP - Patent Security Agreement Executed#page5.tif source=PSP - Patent Security Agreement Executed#page6.tif source=PSP - Patent Security Agreement Executed#page7.tif source=PSP - Patent Security Agreement Executed#page8.tif source=PSP - Patent Security Agreement Executed#page9.tif source=PSP - Patent Security Agreement Executed#page10.tif source=PSP - Patent Security Agreement Executed#page11.tif source=PSP - Patent Security Agreement Executed#page12.tif source=PSP - Patent Security Agreement Executed#page13.tif source=PSP - Patent Security Agreement Executed#page14.tif source=PSP - Patent Security Agreement Executed#page15.tif source=PSP - Patent Security Agreement Executed#page16.tif source=PSP - Patent Security Agreement Executed#page17.tif source=PSP - Patent Security Agreement Executed#page18.tif source=PSP - Patent Security Agreement Executed#page19.tif source=PSP - Patent Security Agreement Executed#page20.tif source=PSP - Patent Security Agreement Executed#page21.tif source=PSP - Patent Security Agreement Executed#page22.tif source=PSP - Patent Security Agreement Executed#page23.tif source=PSP - Patent Security Agreement Executed#page24.tif source=PSP - Patent Security Agreement Executed#page25.tif source=PSP - Patent Security Agreement Executed#page26.tif source=PSP - Patent Security Agreement Executed#page27.tif source=PSP - Patent Security Agreement Executed#page28.tif source=PSP - Patent Security Agreement Executed#page29.tif source=PSP - Patent Security Agreement Executed#page30.tif source=PSP - Patent Security Agreement Executed#page31.tif source=PSP - Patent Security Agreement Executed#page32.tif source=PSP - Patent Security Agreement Executed#page33.tif source=PSP - Patent Security Agreement Executed#page34.tif source=PSP - Patent Security Agreement Executed#page35.tif source=PSP - Patent Security Agreement Executed#page36.tif

source=PSP - Patent Security Agreement Executed#page37.tif source=PSP - Patent Security Agreement Executed#page38.tif source=PSP - Patent Security Agreement Executed#page39.tif

### PATENT SECURITY AGREEMENT

PATENT SECURITY AGREEMENT dated as of January 31, 2019 (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Patent Security Agreement"), made by each of the signatories hereto other than the Collateral Agent (as defined below) (together with any other entity that may become a party hereto as provided herein, the "Grantors"), in favor of BARCLAYS BANK PLC, as collateral agent (in such capacity and together with its successors, the "Collateral Agent") for (i) the banks and other financial institutions or entities (the "Lenders") from time to time parties to the Credit Agreement dated as of January 31, 2019 (as amended, restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), among Platform Specialty Products Corporation, a Delaware limited liability company, MacDermid, Incorporated, a Connecticut corporation, the other guarantors party thereto from time to time, the Lenders and other financial institutions party thereto from time to time, and Barclays Bank PLC, as administrative agent and as collateral agent and (ii) the other Secured Parties.

### WITNESSETH:

WHEREAS, Grantors are party to that certain Pledge and Security Agreement dated as of January 31, 2019 (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Pledge and Security Agreement") made by each of the Grantors and the other grantors party thereto in favor of the Collateral Agent, pursuant to which the Grantors are required to execute and deliver this Patent Security Agreement.

NOW, THEREFORE, in consideration of the premises and to induce the Secured Parties to enter into the Credit Agreement, the Grantors hereby agree with the Collateral Agent, as follows:

SECTION 1. <u>Defined Terms</u>. Unless otherwise defined herein, capitalized terms have the meaning given to them in the Pledge and Security Agreement.

### SECTION 2. Grant of Security Interest in Patent Collateral.

Each Grantor hereby grants to the Collateral Agent, for the ratable benefit of the Secured Parties, a security interest in all of the following property of such Grantor, in each case, wherever located and now owned or at any time hereafter acquired by such Grantor or in which such Grantor now has or at any time in the future may acquire any right, title and interest (collectively, the "Patent Collateral"), as collateral security for the prompt and complete payment and performance when due (whether at the stated maturity, by acceleration, or otherwise) of such Grantor's Obligations:

(i) all letters of patent of the United States, any other country, union of countries or any political subdivision of any of the foregoing, all reissues and extensions thereof, including any of the foregoing listed on Schedule I hereto,

- (ii) all applications for letters of patent of the United States or any other country or union of countries or any political subdivision of any of the foregoing and all divisions, continuations and continuations-in-part thereof, including any of the foregoing listed on Schedule I hereto.
  - (iii) the right to, and to obtain, any reissues or extensions of the foregoing,
- (iv) the right to sue or otherwise recover for past, present and future infringement of any of the foregoing, and
- (v) all Proceeds of the foregoing, including license fees, royalties, income, payments, claims, damages and proceeds of suit;

<u>provided</u> that notwithstanding any other provision set forth in this Section 2, this Patent Security Agreement shall not, at any time, constitute a grant of a security interest in any property that is, at such time, an Excluded Asset.

SECTION 3. The security interest granted pursuant to this Patent Security Agreement is granted in conjunction with the security interest granted to the Collateral Agent for the Secured Parties pursuant to the Pledge and Security Agreement and each Grantor hereby acknowledges and affirms that the rights and remedies of the Collateral Agent with respect to the security interest in the Patent Collateral made and granted hereby are more fully set forth in the Pledge and Security Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein. In the event that any provision of this Patent Security Agreement is deemed to conflict with the Pledge and Security Agreement, the provisions of the Pledge and Security Agreement shall control.

SECTION 4. <u>APPLICABLE LAW</u>. THIS PATENT SECURITY AGREEMENT AND ANY DISPUTE, CLAIM OR CONTROVERSY ARISING OUT OF OR RELATING TO THIS PATENT SECURITY AGREEMENT (WHETHER ARISING IN CONTRACT, TORT OR OTHERWISE) SHALL BE GOVERNED BY, AND CONSTRUED AND INTERPRETED IN ACCORDANCE WITH, THE LAW OF THE STATE OF NEW YORK WITHOUT REGARD TO CONFLICTS OF LAW RULES THAT WOULD RESULT IN THE APPLICATION OF A DIFFERENT GOVERNING LAW (OTHER THAN ANY MANDATORY PROVISIONS OF THE UCC RELATING TO THE LAW GOVERNING PERFECTION AND EFFECT OF PERFECTION OR PRIORITY OF THE SECURITY INTERESTS).

SECTION 5. <u>Counterparts</u>. This Patent Security Agreement may be executed by one of more of the parties to this Patent Security Agreement on any number of separate counterparts (including by facsimile and electronic PDF delivery), and all of said counterparts taken together shall be deemed to constitute one and the same instrument.

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US-DOCS\105643935.1

IN WITNESS WHEREOF, each Grantor has caused this Patent Security Agreement to be executed and delivered by its duly authorized officer as of the date first set forth above.

ALENT, INC.
ALPHA ASSEMBLY SOLUTIONS INC.
(f/k/a/ Alpha Metals Inc.)
MACDERMID ACUMEN, INC.
MACDERMID ENTHONE AMERICA LLC
(f/k/a OMG Electronic Chemicals, LLC)
MACDERMID ENTHONE INC.
(f/k/a Enthone Inc.)
MACDERMID GRAPHICS SOLUTIONS, LLC
(f/k/a MacDermid Printing Solutions, LLC)
MACDERMID OFFSHORE SOLUTIONS, LLC
MACDERMID, INCORPORATED
NAPP SYSTEMS INC.

Ву:

Name: John E. Capps

Title: Secretary

[Signature Page to Patent Security Agreement]

Accepted and Agreed:

BARCLAYS BANK PLC, as Collateral Agent

[Signature Page to Patent Security Agreement]

### US-DOCS\105643935.1

## SCHEDULE I TO ENT SECURITY AGREEMEN

# PATENTS AND PATENT APPLICATIONS:

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
Alent, Inc.	RELEASABLE MICROCAPSULE AND ADHESIVE CURING SYSTEM USING THE SAME	10/271,511	10/16/2002	6,936,644	8/30/2005	Granted
Alpha Assembly Solutions Inc.	Production of Graphene	15/265385	9/14/2016			Published
Alpha Assembly Solutions Inc.	Advanced Solder Alloys for Electronic	15/286759	10/6/2016			Published
Alpha Assembly Solutions Inc.	Method for Manufacturing Metal Powder	15/302712	10/7/2016	10130995	11/20/2018	Granted
Alpha Assembly Solutions Inc.	Stretchable Interconnects for Flexible Electronic Surfaces	15/326224	1/16/2017			Published
Alpha Assembly Solutions Inc.	Low Temperature High Reliability Alloy for Solder Hierarchy	15/326180	1/13/2017			Published
Alpha Assembly Solutions Inc.	Engineered Residue Solder Paste Technology	15/318829	12/14/2016			Published
Alpha Assembly Solutions Inc.	High Reliability Lead-Free Solder Alloy		5/2/2017			Pending
Alpha Assembly Solutions Inc. <sup>1</sup>	Particles and Inks and Films Using Them	13/168465	6/24/2011	9217088	12/22/2015	Granted
Alpha Assembly Solutions Inc.	Conductive Patterns and Methods of Using Them	15/439555	2/22/2017			Published
Alpha Assembly Solutions Inc.	Method for Producing a High Aspect Ratio Conductive Pattern on a Substrate	11/857871	9/19/2007	9615463	4/4/2017	Granted
Alpha Assembly Solutions Inc.	Materials for Use with Interconnectors of Electrical Devices and Related Methods	11/873838	10/17/2007	10123430	11/6/2018	Granted
Alpha Assembly Solutions Inc.	Solder Preforms and Solder Alloy Assembly Methods	15/716963	9/27/2017			Published
Alpha Assembly Solutions Inc.	Solder Preforms and Solder Alloy Assembly Methods	14/386601	3/15/2013	9801285	10/24/2017	Granted
Alpha Assembly Solutions Inc.	Flux Formulations	15/390861	12/27/2016	9751159	9/5/2017	Granted

<sup>&</sup>lt;sup>1</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

Owner  Alpha Assembly Solutions Inc.	Title  Dual Side Reinforcement Flux for Encapsulation	Application No.	Filing Date 1/29/2016	Patent No. 9786629	Issue Date 10/10/2017
Alpha Assembly Solutions Inc. Alpha Assembly Solutions Inc.	Dual Side Reinforcement Flux for Encapsulation Rosin-Free Thermosetting Flux Formulations	14/908986 15/109352	1/29/2016	9786629 6/30/2016	10/10/2017
Alpha Assembly Solutions Inc.	Composite and Multilayered Silver Films for Joining Electrical and Mechanical Components	14/915067	2/26/2016		
Alpha Assembly Solutions Inc.	Lead-Free, Silver-Free Solder Alloys	15/028988	4/13/2016		
Alpha Assembly Solutions Inc.	Electrical Connection Tape	15/549535	8/8/2017		
Alpha Assembly Solutions Inc.	Sintering Materials and Attachment Methods	15/316684	12/6/2016		
Alpha Assembly Solutions Inc.	RF SHIELD WITH SELECTIVELY	15/426320	2/7/2017		
- I	INTEGRATED SOLDER		!		
Alpha Assembly Solutions Inc.	Conductive Compositions and Methods of Using Them	15/148320	5/6/2016	10059827	8/28/2018
Alpha Assembly Solutions Inc.	Conductive Compositions and Methods of Using Them	12/567523	9/25/2009	8564140	10/22/2013
Alpha Assembly Solutions Inc.	Conductive Compositions and Methods of Using Them	14/058553	10/21/2013	9355938	5/31/2016
Alpha Assembly Solutions Inc.	HIGH IMPACT TOUGHNESS ALLOY	15/644331	7/7/2017		
Alpha Assembly Solutions Inc.	HIGH IMPACT SOLDER TOUGHNESS ALLOY	16/003202	6/8/2018		
Alpha Assembly Solutions Inc.	METAL RECOVERY	14/900493	12/21/2015		
Alpha Assembly Solutions Inc.	JOINING TO ALUMINIUM	14/909888	2/3/2016	10065274	9/4/2018
Alpha Assembly Solutions Inc.	Applications of Engineered Graphenes	62/655409	4/10/2018		
Alpha Assembly Solutions Inc.	Sintered Nano Copper Paste and Film	62/689962	6/26/2018		
Alpha Assembly Solutions Inc.	Engineered Flux for Solder Paste				
Alpha Assembly Solutions Inc. <sup>2</sup>	Soldering Flux Vehicle Additive and Fine Pitch Printing Method	10036952	12/21/2001	6936115	8/30/2005
Alpha Assembly Solutions Inc. <sup>3</sup>	Flip chip with integrated flux and underfill	09067381	4/27/1998	6265776	7/24/2001
Alpha Assembly Solutions Inc. 4	Stencil incorporating electronic tag	09231490	1/14/1999	6123024	9/26/2000

<sup>&</sup>lt;sup>2</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>4</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>3</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

PATENT REEL: 049823 FRAME: 0062

	Alpha Assembly Solutions Inc. 15		Alpha Assembly Solutions Inc. 14	Alpha Assembly Solutions Inc. 13	Alpha Assembly Solutions Inc. 12		Alpha Assembly Solutions Inc. 11	Alpha Assembly Solutions Inc. 10		Alpha Assembly Solutions Inc. 9		Alpha Assembly Solutions Inc. 8	Alpha Assembly Solutions Inc. 7	Alpha Assembly Solutions Inc. <sup>6</sup>	Alpha Assembly Solutions Inc. <sup>5</sup>	Ожиег
evaporation	Rapid surface cooling of solder droplets by flash	configuration	Thermal interface material and heat sink	Low-residue, low-solder-ball flux	Soldering Flux	providing two-stage bump formation	Flip chip having integral mask and underfill	Wafer coating method for flip chips	boards	Post-treatment for copper on printed circuit	manufacture	Process for silver plating in printed circuit board	Flip chip with integrated flux and underfill	Flip chip with integrated mask and underfill	Flip chip with integrated mask and underfill	Title
	10363420		10151741	09834196	09728264		09395558	09395553		09345675		09282729	09266232	09266166	092566166	Application No.
	8/15/2003		5/20/2002	4/12/2001	12/1/2000		9/14/1999	9/14/1999		6/30/1999		3/31/1999	3/10/1999	3/10/1999	3/10/1999	Filing Date
	7097806		6653741	6524398	6599372		6228681	6323062		6294220		6319543	6194788	6228678	6228678	Patent No.
	8/29/2006		11/252003	2/25/2003	7/29/2003		5/8/2001	11/27/2001		9/25/2001		11/20/2001	2/27/2001	5/8/2001	5/8/2001	Issue Date
	Granted		Granted	Granted	Granted		Granted	Granted		Granted		Granted	Granted	Granted	Granted	Status

<sup>5</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>6</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

 $^{7}$  Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>8</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>9</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc. <sup>10</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>11</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>12</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>13</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>14</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>15</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

Очист	Tric	Application No.	Filing Date	Patent No.	Issue Date	Status
Alpha Assembly Solutions Inc. 16	Thermoplastic fluxing underfill composition and method	10458925	6/11/2003	7166491	1/23/2007	Granted
Alpha Assembly Solutions Inc. 17	Thermal interface material and solder preforms	10722288	11/25/2003	7187083	3/6/2007	Granted
Alpha Assembly Solutions Inc. 18	UNDERFILL FLUXING CURATIVE	85171801	4/2/2004	7213739	5/8/2007	Granted
Alpha Assembly Solutions Inc. 19	METHOD OF APPLYING A PATTERN OF	10888286	7/9/2004	7585549	9/8/2009	Granted
	PARTICLES TO A SUBSTRATE					
Alpha Assembly Solutions Inc. 20	COATING SOLDER METAL PARTICLES  WITH A CHARGE DIRECTOR MEDITIM	10888619	7/9/2004	7413771	8/19/2008	Granted
Alpha Assembly Solutions Inc. 21	COATED STENCIL WITH REDUCED	10899679	7/26/2004	7093746	8/22/2006	Granted
	SURFACE TENSION					
Alpha Assembly Solutions Inc. 22	LOW VOIDING NO FLOW FLUXING	80611601	8/5/2004	7247683	7/24/2007	Granted
	UNDERFILL FOR ELECTRONIC DEVICES					
Alpha Assembly Solutions Inc. 23	SOLDER PREFORMS FOR USE IN	11012457	12/15/2004	7533793	5/19/2009	Granted
	ELECTRONIC ASSEMBLY					
Alpha Assembly Solutions Inc. 24	Multilayered Metal Nano and Micron Particles	15318895	12/14/2016			Pending
Alpha Assembly Solutions Inc. <sup>25</sup>	Jettable Inks For Solar Cell and Semiconductor	15312799	11/21/2016			Pending
	Fabrication					

<sup>16</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>17</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>18</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>19</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>20</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>21</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>22</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>24</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc. <sup>23</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>25</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

					using the methods	
Pending			9/16/2013	14027530	Methods for attachment and devices produced	Alpha Assembly Solutions Inc. 35
Pending			12/3/2013	14095559	Solvent systems for metals and inks	Alpha Assembly Solutions Inc. 34
Pending			3/21/2014	14236432	High impact toughness solder alloy	Alpha Assembly Solutions Inc. 33
Pending			3/21/2014	14236480	Solder compositions	Alpha Assembly Solutions Inc. 32
					solder joint	
Pending			3/25/2014	14347035	Systems and methods for void reduction in a	Alpha Assembly Solutions Inc. 31
					at high temperatures	
Pending			4/9/2015	14434470	Lead-free and antimony-free tin solder reliable	Alpha Assembly Solutions Inc. 30
Pending			4/28/2015	14438888	Sintering powder	Alpha Assembly Solutions Inc. 29
					at high temperatures	
Pending			4/28/2015	14698450	Lead-free and antimony-free tin solder reliable	Alpha Assembly Solutions Inc. <sup>28</sup>
					at high temperatures	
Pending			10/8/2015	14878056	Lead-free and antimony-free tin solder reliable	Alpha Assembly Solutions Inc. <sup>27</sup>
Pending			10/7/2016	15302827	Low Pressure Sintering Powder	Alpha Assembly Solutions Inc. <sup>26</sup>
Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner
						Francisco de la companya del companya de la companya del companya de la companya

<sup>27</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc <sup>26</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>35</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>29</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc. <sup>28</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>30</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>32</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc. <sup>31</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>33</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>34</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

Pending
PATENT
REEL: 049823 FRAME: 0065

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
Alpha Assembly Solutions Inc. 36	Sintering materials and attachment methods	13287820	11/2/2011			Pending
Alpha Assembly Solutions Inc. 37	Flux formulations	12497065	7/2/2009			Pending
Alpha Assembly Solutions Inc. 38	Process for silver plating in printed circuit board manufacture	13471203	5/14/2012	RE45279	12/9/2014	Granted
Alpha Assembly Solutions Inc. 39	Process for silver plating in printed circuit board manufacture	13655159	10/18/2012	RE45175	10/7/2014	Granted
Alpha Assembly Solutions Inc. 40	Flux formulations	14077995	11/12/2013	9566668	2/14/2017	Granted
Alpha Assembly Solutions Inc. 41	Electrical contacts	12052104	3/20/2008	9362424	6/7/2016	Granted
Alpha Assembly Solutions Inc. 42	Solder alloy	11720578	7/25/2008	9221131	12/29/2015	Granted
Alpha Assembly Solutions Inc. 43	Solder alloy	12036497	2/25/2008	8641964	2/4/2014	Granted
Alpha Assembly Solutions Inc. 44	Solvent systems for metals and inks	11857818	9/19/2007	8597548	12/3/2013	Granted
Alpha Assembly Solutions Inc. 45	Methods of attaching a die to a substrate	12175375	7/17/2008	8555491	10/15/2013	Granted
Alpha Assembly Solutions Inc. 46	Methods for producing electrical conductors	12052166	3/20/2008	8312623	11/20/2012	Granted

<sup>37</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc. <sup>36</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>39</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc <sup>38</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>40</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>41</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>42</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>43</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>44</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>46</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc <sup>45</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

Alpha Assembly Colutions Inc.   Mathad	Alpha Assembly Solutions Inc.  Advanced So Interconnects	Alpha Assembly Solutions Inc.  Materials devices 2	Alpha Assembly Solutions Inc. 55 Preparati electroki	Alpha Assembly Solutions Inc. 54 Coated s	Alpha Assembly Solutions Inc. 53 Thermal	Alpha Assembly Solutions Inc. Mask and patte	metallization	Alpha Assembly Solutions Inc. 51   Electrofc	Alpha Assembly Solutions Inc. 50 Particles		Alpha Assembly Solutions Inc. 49 Reducing	Alpha Assembly Solutions Inc. " Metallic electrostic		Alpha Assembly Solutions Inc. 47   Electrica	Constant.	Owner
Method for Die and Clip Attachment	Advanced Solder Alloys For Electronic Interconnects	Materials for use with interconnects of electrical devices and related methods	Preparation of metallic particles for electrokinetic or electrostatic deposition	Coated solder metal particles	Thermal interface material and solder preforms	Mask and method for electrokinetic deposition and patterning process on substrates	ation	Electroformed stencils for solar cell front side	Particles and inks and films using them	soldering processes	Reducing joint embrittlement in lead-free	Metallic particles for electrokinetic or electrostatic deposition	g them	Electrical conductors and methods of making	*****	Title
15545607	15286759	11873838	11065764	12191710	11682729	11419128		12201654	11462089		12036604	12191691		12175381	No.	Application
7/21/2017	10/6/2016	10/17/2007	2/25/2005	8/14/2008	3/6/2007	5/18/2006		8/29/2008	8/3/2006		2/25/2008	8/14/2008		7/17/2008	a ming water	Filian Date
		10123430	7413805	7655304	7663242	(6/8255		7749883	7968008		8191757	8252417		8304062		Partant Na
		11/6/2018	8/19/2008	2/2/2010	2/16/2010	3/16/2010		7/6/2010	6/28/2011		6/5/2012	8/28/2012		11/6/2012	TOWNER STATES	Igenso Dato
Pending	Pending	Granted	Granted	Granted	Granted	Granted	!	Granted	Granted		Granted	Granted <b>TEI</b>		Granted	Status	Centure

<sup>47</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>55</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>48</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>49</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>50</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>51</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>52</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>53</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc

<sup>&</sup>lt;sup>54</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

Pending

Inc.         Engineered Polymer-Based Electronic Materials         1562 150 290 27/2017         Patent No.         Issue Date           s Inc. 50         Simering Materials and Attachment Methods         156/2195         9/27/2017         9/27/2017         9/27/2017         156/2195         9/27/2017         156/2195         9/27/2017         156/2195         9/27/2017         156/2195         9/27/2017         156/2195         9/27/2018         151/2017         156/2195         9/27/2018         151/2018         151/2018         151/2018         151/2018         151/2018         151/2018         151/2018         151/2019		Granted	4/30/2002	63/9/50	11/22/2000	09//18910	Process for Enhancing the Adhesion of Organic Coatings to Metal Surfaces	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Materials         15562195         9/27/2017         Patent No.         Issue Date         Pending           s Inc. **         Sintering Materials and Attachment Methods         15562195         9/27/2017         Pending         Pending           s Inc. **         High Impact Solder Toughness Alloy         1541954         1/30/2017         Pending           s Inc. **         Lead-Free Solder Compositions         62785293         12/27/2018         Pending           s Inc. **         Lead-Free Solder Compositions         62785293         12/27/2018         Pending           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/274641         3/23/1999         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Organic Coatings to Metal Surfaces         09/421204         10/21/1999         6206981         3/27/2001         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/590046         6/8/2000         6383272         5/7/2002         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/5908857         6/21/2000         6419784         4/29/2003         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	1	Granted	7/17/2001	6261381	11/9/2000	09/710976	Composition and Process for Cleaning Inks from Various Substrates Including Printing Plates	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Malerials         1562.95         9/27/2017         Patent No.         Issue Date         Status           s Inc. 56         Engineered Polymer-Based Electronic Malerials         1562.95         9/27/2017         Pending         Pending           s Inc. 56         Using Same         15419564         1/30/2017         Pending         Pending           s Inc. 57         High Impact Solder Compositions         62785293         12/27/2018         6162503         12/19/2000         Pending           s Inc. 58         Lead-Free Solder Compositions         62785293         12/27/2018         6162503         12/19/2000         Pending           Process for Improving the Adhesion of Process for Improving the Adhesion of Coatings to Metal Surfaces         09/274641         3/23/1999         6162503         3/27/2001         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         2/27/2002         6503566         1/7/2003         Granted Polymeric Materials to Metal Surfaces           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/598857         6/21/2000         6419784         7/16/2002         Granted Polymeric Materials to Metal Surfaces		Granted	7/9/2002	6417149	9/7/2001	09/949191	Paint Stripping Composition and Process Containing Methyl Benzoate and Formic Acid	MacDermid Acumen, Inc.
s Inc.         Engineered Polymer-Based Electronic Materials         15562195         9/27/2017         Patent No.         Issue Date         Pending           s Inc.         Sintering Malerials and Attachment Methods         15017975         2/8/2016         9/27/2017         Pending           s Inc.         High Impact Solder Toughness Alloy         15419564         1/30/2017         Pending         Pending           s Inc.         High Impact Solder Compositions         62785293         12/27/2018         Pending         Pending           s Inc.         High Impact Solder Compositions         62785293         12/27/2018         Pending         Pending           s Inc.         High Impact Solder Compositions         609274641         3/23/1999         6162503         12/19/2000         Pending           process for Improving the Adhesion of Organic         09/274641         10/21/1999         6206981         3/27/2001         Granted           Process for Improving the Adhesion of Dylmeric Materials to Metal Surfaces         09/390046         6/8/2000         6383272         5/7/2002         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         10/09/048         2/27/2002         6503566         1/7/2003         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal		Granted	12/2/2003	6656370	10/13/2000	09/687880	Method for the Manufacture of Printed Circuit Boards	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Materials         15562195         9/27/2017         Pattent No.         Issue Date         Pending           s Inc. 50         Sintering Materials and Attachment Methods         15017975         2/8/2016         15017975         2/8/2016         Pending           s Inc. 57         High Impact Solder Toughness Alloy         15419564         1/30/2017         170/2018         Pending           s Inc. 58         Lead-Free Solder Compositions         62785293         12/17/2018         6162503         12/19/2000         Pending           s Inc. 58         Lead-Free Solder Compositions         62785293         12/17/2018         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Organic Olymeric Materials to Metal Surfaces         09/274641         3/23/1999         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Organic Olymeric Materials to Metal Surfaces         09/421204         10/21/1999         6206981         3/27/2001         Granted           Polymeric Materials to Metal Surfaces         09/59046         6/8/2000         6383272         5/7/2002         Granted           Polymeric Materials to Metal Surfaces         10/09048         2/27/2002         6503566         1/7/2003         Granted		Granted	11/5/2002	6474536	9/28/2000	09/672577	Flux Composition and Corresponding Soldering Method	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Materials s Inc. 56         Losting Materials and Attachment Methods         15562195         9/27/2017         Patent No.         Issue Date           Is Inc. 56         Sintering Materials and Attachment Methods         15017975         2/8/2016         9/27/2017         Pending           Is Inc. 57         High Impact Solder Toughness Alloy         15419564         1/30/2017         Pending         Pending           Inc. 58         Lead-Free Solder Compositions         62788293         12/27/2018         Pending         Pending           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/274641         3/23/1999         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Coatings to Metal Surfaces         09/421204         10/21/1999         6206981         3/27/2001         Granted           Polymeric Materials to Metal Surfaces         09/590046         6/8/2000         6383272         5/7/2002         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         10/090048         2/27/2002         6503566         11/7/2003         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/598857         6/21/2000         6419784         7/16/2002         Granted		Granted	4/23/2002	6375822	10/3/2000	09/677904	Method for Enhancing the Solderability of a Surface	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Materials of Inc. Sintering Materials and Attachment Methods         15562195 15017975         9/27/2017         Patent No.         Issue Date         Pending Pending           s Inc. Sinc. Sintering Materials and Attachment Methods         15017975         2/8/2016         9/27/2017         Pending         Pending           s Inc. Sintering Materials and Attachment Methods         15017975         2/8/2016         Pending         Pending           s Inc. Sintering Materials and Attachment Methods         15419564         1/30/2017         Pending         Pending           s Inc. Sintering Materials and Attachment Methods         62785293         12/27/2018         Pending         Pending           s Inc. Sintering Materials to Metal Surfaces         62785293         12/27/2018         6162503         12/19/2000         Pending           Process for Improving the Adhesion of Organic         09/274641         10/21/1999         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/59046         6/8/2000         6383272         5/7/2002         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         10/090048         2/27/2002         6503566         1/7/2003         Granted           Process for Improvi		Granted	4/29/2003	6554948	8/22/2000	09/643813	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
Inc.         Engineered Polymer-Based Electronic Materials         15562195         9/27/2017         Patent No.         Issue Date         Pending           s Inc. 56         Sintering Materials and Attachment Methods         15017975         2/8/2016         4         Pending           s Inc. 57         High Impact Solder Toughness Alloy         15419564         1/30/2017         4         Pending           s Inc. 57         High Impact Solder Compositions         62785293         1227/2018         4         Pending           s Inc. 58         Lead-Free Solder Compositions         62785293         1227/2018         4         Pending           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/274641         3/23/1999         6162503         12/19/2000         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/421204         10/21/1999         6206981         3/27/2001         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         09/590046         6/8/2000         6383272         5/7/2002         Granted           Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces         10/090048         2/27/2002         6503566         1/7/2003         Granted		Granted	7/16/2002	6419784	6/21/2000	09/598857	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
Inc. Engineered Polymer-Based Electronic Materials 15562195 9/27/2017 Patent No. Engineered Polymer-Based Electronic Materials 1562195 9/27/2017 Patent No. Engineered Polymer-Based Electronic Materials 1562195 9/27/2017 Pending S Inc. Status Inc.		Granted	1/7/2003	6503566	2/27/2002	10/090048	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
Inc. Engineered Polymer-Based Electronic Materials 15562195 9/27/2017 9/27/2017 Pending Is Inc. Sintering Materials and Attachment Methods 15017975 2/8/2016 Pending Is Inc. Thigh Impact Solder Toughness Alloy 15419564 1/30/2017 Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces 109/421204 10/21/1999 6206981 3/27/2001 Granted Granted Granted Coatings to Metal Surfaces		Granted	5/7/2002	6383272	6/8/2000	09/590046	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
Sinc. Engineered Polymer-Based Electronic Materials 15562195 9/27/2017 9/2017 Pending Sintering Materials and Attachment Methods Using Same Sinc. Figh Impact Solder Toughness Alloy 15419564 1/30/2017 Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces  Application Fifting Date Patent No. Issue Date Pending 9/27/2017 Patent No. Issue Date Pending Pending 15017975 2/8/2016 Patent No. Issue Date Pending Pending Pending 15017975 2/8/2016 Pending Pending Pending 15419564 1/30/2017 Pending Pending Pending Polymeric Materials to Metal Surfaces		Granted	3/27/2001	6206981	10/21/1999	09/421204	Process for Enhancing the Adhesion of Organic Coatings to Metal Surfaces	MacDermid Acumen, Inc.
Engineered Polymer-Based Electronic Materials 15562195 9/27/2017 Pending Sintering Materials and Attachment Methods Using Same 15419564 1/30/2017 Pending 12419564 1/30/2018 Pending P	F	Granted	12/19/2000	6162503	3/23/1999	09/274641	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
Engineered Polymer-Based Electronic Materials       15562195       9/27/2017       Patent No.       Issue Date       Pending         Sintering Materials and Attachment Methods       15017975       2/8/2016       Pending         Using Same       15419564       1/30/2017       Pending	PA	Pending			12/27/2018	62785293	Lead-Free Solder Compositions	Alpha Assembly Solutions Inc. 58
Fifte       Application No.       Filing Date No.       Patent No.       Issue Date         Engineered Polymer-Based Electronic Materials       15562195       9/27/2017       9/27/2016       Pending         Sintering Materials and Attachment Methods       15017975       2/8/2016       Pending         Using Same       Pending       Pending	T	Pending			1/30/2017	15419564	High Impact Solder Toughness Alloy	Alpha Assembly Solutions Inc. 57
Title       Application No.       Filing Date       Patent No.       Issue Date       Status         Engineered Polymer-Based Electronic Materials       15562195       9/27/2017       Pending	ENT	Pending			2/8/2016	15017975	Sintering Materials and Attachment Methods Using Same	Alpha Assembly Solutions Inc. 56
Title Application Filing Date Patent No. Issue Date	•	Pending			9/27/2017	15562195	Engineered Polymer-Based Electronic Materials	Alpha Assembly Solutions Inc.
		Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner

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<sup>&</sup>lt;sup>56</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>57</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>58</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Acumen, Inc.	Process & Composition for High Speed Plating of Tin & Tin Alloys	09/965743	9/28/2001	6562221	5/13/2003	Granted
MacDermid Acumen, Inc.	Method for the Manufacture of Printed Circuit Boards with Plated Resistors	09/784242	2/15/2001	6585904	7/1/2003	Granted
MacDermid Acumen, Inc.	Method for the Manufacture of Printed Circuit Boards with Plated Resistors	10/419651	4/21/2003	7034231	4/25/2006	Granted
MacDermid Acumen, Inc.	High Temperature Continuous Eloectrodialysis of Electroless Plating Solutions	09/788766	2/20/2001	6391177	5/21/2002	Granted
MacDermid Acumen, Inc.	Composition & Method for Inhibiting Corrosion of Aluminum & Aluminum Alloys Using Mercapto Substituted Silanes	09/802087	3/8/2001	6461682	10/8/2002	Granted
MacDermid Acumen, Inc. 59	Electroplating Composition and Process	09/803631	3/9/2001	6582582	6/24/2003	Granted
MacDermid Acumen, Inc. 60	Composition and Process for Inhibiting Corrosion of Metallic Substrates	09/906370	7/16/2001	6508958	1/21/2003	Granted
MacDermid Acumen, Inc.	Composition and Process for Inhibiting Corrosion of Metallic Substrates	10/328197	12/23/2002	6706214	3/16/2004	Granted
MacDermid Acumen, Inc.	Electroless Nickel Plating Solution & Process for its Use	09/945011	8/31/2001	6500482	12/31/2002	Granted
MacDermid Acumen, Inc.	Non-Chrome Passivation Process for Zinc & Zinc Alloys	09/938234	8/23/2001	6524403	2/25/2003	Granted
MacDermid Acumen, Inc.	Process for Plating Particulate Matter	09/946404	9/5/2001	6586047	7/1/2003	Granted
MacDermid Acumen, Inc.	Noncyanide Copper Plating Process for Zinc & Zinc Alloys	10/096411	3/12/2002	6827834	12/7/2004	Granted
MacDermid Acumen, Inc.	Magnesium Conversion Coating Composition and Method of Using Same	10/076897	2/14/2002	6692583	2/17/2004	Granted
MacDermid Acumen, Inc.	Method of Stripping Silver from a Printed Circuit Board	10/106522	3/25/2002	6783690	8/31/2004	Granted
MacDermid Acumen, Inc.	Method for the Manufacture of Printed Circuit Boards with Integral Plated Resistors	10/271817	10/16/2002	6767445	7/27/2004	Granted
MacDermid Acumen, Inc.	Method of Fabricating Electronic Interconnect Devices Using Direct Imaging of Dielectric Composite Material	10/372747	2/24/2003	6762073	7/13/2004	Granted

<sup>&</sup>lt;sup>59</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

<sup>&</sup>lt;sup>60</sup> Appropriate documentation to be filed with the USPTO to update owner name from Alpha Metals, Inc.

		MacDermid Acumen, Inc. Copper E	MacDermid Acumen, Inc. Polyimid Manufact Same	MacDermid Acumen, Inc.  Microetci the Same	MacDermid Acumen, Inc. Microetci the Same		MacDermid Acumen, Inc. Method c	MacDermid Acumen, Inc. Microetci	MacDermid Acumen, Inc.  Pretreatment o Electroplating	MacDermid Acumen, Inc. Controllii Copper C		Comprisi	MacDermid Acumen, Inc. Integral F	MacDermid Acumen, Inc. Selective Conducti	MacDermid Acumen, Inc. Process f Substrate	MacDermid Acumen, Inc.  Methods  Manufact	MacDermid Acumen, Inc.  Protective Media	MacDermid Acumen, Inc.  Method o Substrate	•	MacDermid Acumen, Inc. Coating f	Owner
Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	Process for Electrolytically Plating Copper	Copper Electroplating of Printing Cylinders	Polyimide Substrate and Method of Manufacturing Printed Wiring Board Using the Same	Microetching Composition and Method of Using the Same	Microelching Composition and Method of Using the Same	Developer Solution and Process for Use	Method of Using Ultrasonics to Plate Silver	Microetching Solution	Pretreatment of Magnesium Substrates for Electroplating	Controlling the Hardness of Electrodeposited  Copper Coatings by Variation of Current Profile	Process for Preparing a Non-Conductive Substrate for Electroplating	Comprising the Same	Integral Plated Resistor and Method for the Manufacture of Printed Circuit Boards	Selective Catalytic Activation of Non- Conductive Substrates	Process for Preparing a Non-Conductive Substrate for Electroplating	Methods of Cleaning Copper Surfaces in the Manufacture of Printed Circuit Boards	Protective U.V. Curable Cover Layer for Optical Media	Method of Forming a Metal Pattern on a Substrate	Polytetrafluoroethylene Dispersion for Electroless Nickel Plating Applications	Coating for Silver Plated Circuits	Title
11/503780	11/398048	11/403628	11/386631	11/893068	11/316010	11/290118	11/300254	11/209471	11/205516	10/943113	10/964212		10/925589	10/837109	10/798522	10/705026	10/694375	10/820236	10/431251	10/412932	Application No.
8/14/2006	4/5/2006	4/13/2006	3/22/2006	8/14/2007	12/21/2005	11/30/2005	12/14/2005	8/23/2005	8/17/2005	9/16/2004	10/13/2004		8/25/2004	4/30/2004	3/11/2004	11/10/2003	10/27/2003	4/6/2004	5/7/2003	4/14/2003	Filing Date
7704562	7575666	7153408	7666471	7875558	/456114	7094523	7429400	7393461	7704366	7329334	7214304		7022464	7255782	7128820	7063800	6972143	73/8225	6837923	6773757	Patent No.
4/27/2010	8/18/2009	12/26/2006	2/23/2010	1/25/2011	11/25/2008	8/22/2006	9/30/2008	7/1/2008	4/27/2010	2/12/2008	5/8/2007		4/4/2006	8/14/2007	10/31/2006	6/20/2006	12/6/2005	5/2//2008	1/4/2005	8/10/2004	Issue Date
Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted		Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

	Granted	6/30/2015	9067238	1/15/2013	13/741446	Method for Improving Plating on Non- Conductive Substrates	MacDermid Acumen, Inc.
I	Granted	11/13/2012	8308893	2/1/2010	12/697425	Nano-Oxide Process for Bonding Copper/Copper Alloy and Resin	MacDermid Acumen, Inc.
	Granted	12/25/2012	8337942	7/22/2011	13/188615	Light Induced Electroless Plating	MacDermid Acumen, Inc.
	Granted	5/13/2014	8722142	8/28/2009	12/549547	Light Induced Electroless Plating	MacDermid Acumen, Inc.
	Granted	2/17/2015	8956687	11/20/2012	13/681722	Light Induced Plating of Metals on Silicon Photovoltaic Cells	MacDermid Acumen, Inc.
	Oranica	// 10/2015	0+00201	10/2/2007	12/3/3236	Wiring Boards	
	Granted	8/2/2011	7989346	10/5/2009	12/509619	Surface Treatment of Silicon	MacDermid Acumen, Inc.
	Granted	3/10/2015	8974860	6/19/2009	12/488158	Selective Deposition of Metal on Plastic Substrates	MacDermid Acumen, Inc.
	I dousied			9/10/201/	15/0/0//1	Resistance to Corrosion in Calcium Chloride Environments	May Donney, nic.
	Daklichad			9/16/2017	15/679771	Chromium Allar Coating with Enhanced	MaDamid Aguman Ina
	Granted	9/19/201/	9/6543/	3/24/2009	12/409629	Chromium Alloy Coating with Enhanced Resistance to Corrosion in Calcium Chloride	MacDermid Acumen, Inc.
1	Granted	9/11/2012	8263177	3/27/2009	12/383650	Organic Polymer Coatings for Protection Against Creep Corrosion	MacDermid Acumen, Inc.
	Granted	8/20/2013	8512504	5/6/2009	12/436260	Process for Improving Adhesion of Polymeric  Materials to Metal Surfaces	MacDermid Acumen, Inc.
	Granted	8/24/2010	7780840	10/30/2008	12/261352	Process for Plating Chromium from a Trivalent Chromium Plating Bath	MacDermid Acumen, Inc.
1	Granted	12/15/2009	7631798	10/2/2008	12/244136	Method for Enhancing the Solderability of a Surface	MacDermid Acumen, Inc.
	Granted	5/15/2012	8177956	3/12/2008	12/046864	Method of Electrolytically Dissolving Nickel into Electroless Nickel Plating Solutions	MacDermid Acumen, Inc.
1	Granted	8/27/2013	8518281	6/3/2008	12/156613	Acid-Resistance Promoting Composition	MacDermid Acumen, Inc.
	Granted	1/3/2012	8088246	1/8/2009	12/350380	Process for Improving the Adhesion of Polymeric Materials to Metal Surfaces	MacDermid Acumen, Inc.
	Granted	2/15/2011	7887693	6/22/2007	11/821206	Acid Copper Electroplating Bath Composition	MacDermid Acumen, Inc.
	Granted	11/16/2010	7833583	3/27/2007	11/728757	Method of Recycling Electroless Nickel Waste	MacDermid Acumen, Inc.
	Granted	1/12/2010	7645393	4/27/2007	11/796660	Metal Surface Treatment Composition	MacDermid Acumen, Inc.
	Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner
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MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	MacDermid Acumen, Inc.	Омпег
Electroless Nickel Plating Solution and Method	Regeneration of Etch Solutions Containing Trivalent Manganese in Acid Media	Additives for Producing Copper Electrodeposits Having Low Oxygen Content	Etching of Plastic Using Acidic Solutions Containing Trivalent Manganese	Electrolytic Generation of Manganese (III) Ions in Strong Sulfuric Acid	Etching of Plastic Using Acidic Solutions Containing Trivalent Manganese	Electrolytic Generation of Manganese (III) Ions in Strong Sulfuric Acid Using an Improved Anode	Etching of Plastic Using Acidic Solutions Containing Trivalent Manganese	Etching of Plastic Using Acidic Solutions Containing Trivalent Manganese	Color Control of Trivalent Chromium Deposits	Adhesion Promoting Composition for Metal Leadframes	Adhesion Promoting Composition for Metal Leadframes	Aluminium Treatment Compositions	Electrolytic Dissolution of Chromium from Chromium Electrodes	Dark Colored Chromium Based Electrodeposits	Dark Colored Chromium Based Electrodeposits	Method of Producing Polymeric Phenazonium Compounds	Improved Method of Producing Polymeric Phenazonium Compounds	Improved Method of Producing Polymeric Phenazonium Compounds	Method for Improving Plating on Non- Conductive Substrates	Title
13/961018	13/870232	13/480887	15/934127	13/795382	13/356004	13/677798	15/357385	14/467105	13/398111	13/018668	13/954328	13/021026	12/947059	12/940249	13/593690	12/890013	13/238832	14/181866	12/693548	Application No.
8/7/2013	4/25/2013	5/25/2012	3/23/2018	3/12/2013	1/23/2012	11/15/2012	11/21/2016	8/25/2014	2/16/2012	2/1/2011	7/30/2013	2/4/2011	11/16/2010	11/5/2010	8/24/2012	9/24/2010	9/21/2011	2/17/2014	1/26/2010	Filing Date
		9243339		9534306		9752241			9758884	8524540	9030008	8496762	8512541	8273235	9347144	8691987	8735580	9040700	8974869	Patent No.
		1/26/2016		1/3/2017		9/5/2017			9/12/2017	9/3/2013	5/12/2015	7/30/2013	8/20/2013	9/25/2012	5/24/2016	4/8/2014	5/27/2014	5/26/2015	3/10/2015	Issue Date
Published	Appealed	Granted	Published	Granted	Published	Granted	Published	Published	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

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	MacDermid Acumen, Inc.  Process for improving Adhesion of Polymetric 12430200 3/0/2009 8312304  Materials to Metal Surfaces  MacDermid Acumen, Inc.	Method of electrolytically dissolving nickel into 12046864 3/12/2008 electroless nickel plating solutions	MacDermid Acumen, Inc.  Microetching composition and method of using 11893068 8/14/2007 7875558	MacDermid Acumen, Inc.  Polyimide substrate and method of 11386631 3/22/2006 766471  manufacturing printed wiring board using the same	MacDermid Acumen, Inc. Method of using ultrasonics to plate silver 11300254 12/14/2005 7429400	MacDermid Acumen, Inc.  Controlling the hardness of electrodeposited 10943113 9/16/2004 7329334  copper coatings by variation of current profile	MacDermid Acumen, Inc.  Method for the manufacture of printed circuit  boards with plated resistors  11348941  2/6/2006  7279108	MacDermid Acumen, Inc. Process for preparing a non-conductive substrate 10964212 10/13/2004 7214304	MacDermid Acumen, Inc. Process for improving the adhesion of polymeric 10304514 11/26/2002 7186305 materials to metal surfaces	MacDermid Acumen, Inc.  Integral plated resistor and method for the manufacture of printed circuit boards comprising the same	MacDermid Acumen, Inc.  Direct imaging process for forming resist pattern  on a surface, and use thereof in fabricating  printing plates    10190873   7/8/2002   6632588	MacDermid Acumen, Inc.  Process for improving the adhesion of polymeric materials to metal surfaces  09598857 6/21/2000 6419784	MacDermid Acumen, Inc. Fluxing agents for the reflowing of electro- 09147972 11/3/1999 6409850 deposited timplate	MacDermid Acumen, Inc.  Method for the manufacture of printed circuit  boards with plated resistors  09603978  6/27/2000  6281090	MacDermid Acumen, Inc.Tin plating electrolyte compositions0905178412/17/19986217738	Owner Title Application Filing Date Patent No.
3/2/1999 6419340								·								
7/16/2002	8/20/2013	5/15/2012	1/25/2011	2/23/2010	9/30/2008	2/12/2008	10/9/2007	5/8/2007	3/6/2007	4/4/2006	10/14/2003	7/16/2002	6/25/2002	8/28/2001	4/17/2001	Issue Date
Granted	Crained	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics  Process Process Process Process Process of Platings Platings Platings Platings Process for Recovering Catalytic Procious Metal from Aqueous Galvanic Processing Solution Use of Water Soluble and Air Stable Phosphadamantanes as stabilizer in Electrolytes for Electroless Metal Deposition Use of water soluble lanthanide compounds as stabilizer in electrolytes for electroles Metal Deposition Use of water soluble lanthanide compounds as stabilizer in Electrolytes for Electroless Metal Deposition Use of water soluble lanthanide compounds as stabilizer in Electrolytes for electroless metal deposition Use of water soluble lanthanide compounds as stabilizer in Electrolytes for Electroless Metal Deposition Use of water soluble lanthanide compounds as stabilizer in Electrolytes for electroless metal deposition Use of water soluble Influence of Microelectronics  Leveler Compositions for use in Copper Pillars in the Manufacture of Microelectronics  Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics  Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics  In Use of Microelectronics  Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics  In Use of Microelectronics  In Use of Water Soluble Influence I	Granted	7/10/2018	10021782	2/5/2014	13/882330	DEPOSITION OF CONDUCTIVE	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process   Plexible Color Adjustment for Dark CR (III)   15762599   9/23/2016	Granted	9/5/2017	9752074	5/1/2015	14/702020	CHROMIUM-FREE PICKLE FOR PLASTIC SURFACES	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process	Granted	7/10/2018	10017863	6/21/2007	11/766642	CORROSION PROTECTION OF BRONZES	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Phocass Process Process Process Process Plating on Plastics Plating on Plastics Platings Plating Platings Platings Platings Platings Platings Platings Process for Recovering Catalytic Precious Metal From Aqueous Calwanic Processing Solution Processing Solution Processing Solution Use of Water Soluble and Air Stable Phosphadamantanes as stabilizer in Electrolytes for Electroless Metal Deposition Use of Vater Soluble Indianade compounds as stabilizer in electrolytes for electroless metal deposition Cobalt Filling of Interconnects of Microelectronics Leveler Compositions for use in Copper Platas in Los/17422 (8/2017) Process for Metalization of Copper Platas in Los/17482 (8/2017) Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics Leveler Composition in Manufacture of Microelectronics SILVER PLATING IN ELECTRONICS 15/412809 1/23/2017 (8/2017) Process Deposition in Manufacture of Microelectronics 15/412809 1/23/2017 (8/2017) Process for Metalization of Copper Platas in 15/617482 (8/2017) (8/2017) Process for Microelectronics 15/412809 1/23/2017 (8/2017) Process for Microelectronics 15/412809 1/23/2017 (8/2017) (8/2017) Process for Microelectronics 15/412809 1/23/2017 (8/2017) (8/20	Granted	11/3/2009	7,611,987	10/5/2005	11/243,624	DEFECTIVITY AND PROCESS CONTROL OF ELECTROLESS DEPOSITION IN MICROELECTRONICS APPLICATIONS [Cobalt]	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics   Process   Proce	Granted	11/3/2009	7,611,988	10/5/2005	11/243,631	DEFECTIVITY AND PROCESS CONTROL OF ELECTROLESS DEPOSITION IN MICROELECTRONICS APPLICATIONS [Cobalt]	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Princests Process Chrome Free Etches in a Plating on Plastics Patings  Flexible Color Adjustment for Dark CR (III)  System and Process for Recovering Catalytic Precisions Metal from Aqueous Galvanic Processing Solution  Use of Water Soluble and Air Stable Phosphadamantanes as stabilizer in electrolytes for electroless metal deposition  Cobalt Filling of Interconnects  Leveler Compositions for use in Copper Pillars in Deposition in Manufacture of Microelectronics  Cobalt Filling of Interconnects in Microelectronics  Cobalt Filling of Interconnects in S15/739314	Granted	8/8/2017	9730321	3/24/2015	14/666990	SILVER PLATING IN ELECTRONICS  MANUFACTURE [Silver]	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process  Flexible Color Adjustment for Dark CR (III)  Platings  System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic  Processing Solution  Use of Water Soluble and Air Stable Phosphadamantanes as stabilizer in electrolytes for electroless metal deposition  Use of water soluble lambanide compounds as stabilizer in electrolytes for electroless metal deposition  Cobalt Filling of Interconnects  Process for Metallization of Copper Pillars in the Manufacture of Microelectronics  Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics  Manufacture of Microelectronics  Application of Pillars in 15/5152017  Pattern No. Issue Datte  Pattern No. Issue Dattern No. Issue D	Pending			6/30/2016	15/739314	Cobalt Filling of Interconnects in Microelectronics	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process  Flexible Color Adjustment for Dark CR (III) Platings  . Flexible Color Adjustment for Dark CR (III) Platings  . System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic Processing Solution Use of Water Soluble and Air Stable Phosphaadamantanes as stabilizer in Electrolytes for Electroless Metal Deposition Use of water soluble lanthanide compounds as stabilizer in electrolytes for electroless metal deposition Cobalt Filling of Interconnects Process for Metallization of Copper Pillars in the Manufacture of Microelectronics  Applitude Praint No. Issue Datte  Bystem Using Datte Plants  15/6259 9/23/2016 15/76259 9/23/2016 15/754224 8/15/2016 15/754224 8/15/2016 15/754224 8/15/2016 15/765637 10/6/2016 15/765637 10/6/2016 15/765637 10/6/2017	Published			1/23/2017	15/412809	Leveler Compositions for use in Copper Deposition in Manufacture of Microelectronics	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process Process Flexible Color Adjustment for Dark CR (III) Platings System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic Processing Solution Use of Water Soluble and Air Stable Phosphadamantanes as stabilizer in Electrolytes for electroless metal deposition Cobalt Filling of Interconnects  Application Filing Date Patient No.  Issue Date Patient No. Issue Date Isolated No. Isolated No. Isolated No. Isolated No. Isolated No. Iso	Pending			6/8/2017	15/617482	Process for Metallization of Copper Pillars in the Manufacture of Microelectronics	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Eiches in a Plating on Plastics Process  Flexible Color Adjustment for Dark CR (III)  System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic Processing Solution  Use of Water Soluble and Air Stable Phosphaadamantanes as stabilizer in Electroless Metal Deposition  15/765637  15/765637  15/765637  10/6/2016  Processing Solution  15/765637  10/6/2016  15/765637  10/6/2016  15/765637  10/6/2017	Pending			7/5/2017	15/641756	Cobalt Filling of Interconnects	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process  Flexible Color Adjustment for Dark CR (III) Platings  System and Process for Recovering Catalytic Precious Metal from Aqueous Galvamic Processing Solution  Use of Water Soluble and Air Stable Phosphaadamantanes as stabilizer in Electrolytes for Electroless Metal Deposition  Light Ment No. Issue Date Patent No. Issue Date  Plating Plating Patent No. Issue Date  Plating Plating Plate No. Issue Date  Plating Plating Plate No. Issue Date  Plating Plating Plate No. Issue Date  Plating Plate No. Issue Date  Plating Pla	Published			6/7/2017	15/616540	Use of water soluble lanthanide compounds as stabilizer in electrolytes for electroless metal deposition	MacDermid Enthone Inc.
Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process Flexible Color Adjustment for Dark CR (III) Platings System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic Processing Solution  Application Filing Date Patent No.  Application Filing Date Patent No.  Issue Date Patent No.  Application  15551052 8/15/2017 15762599 9/23/2016 15/762599 9/23/2016 15/754224 8/15/2016	Pending			10/6/2016	15/765637	Use of Water Soluble and Air Stable Phosphaadamantanes as stabilizer in Electrolytes for Electroless Metal Deposition	MacDermid Enthone Inc.
Title  Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics  Process Flexible Color Adjustment for Dark CR (III)  Platings  Application Filing Date  Patent No.  Issue Date Patent No.  Plating Date  Patent No.  Issue Date  Patent No.  Issue Date  Patent No.  Issue Date	Published			8/15/2016	15/754224	System and Process for Recovering Catalytic Precious Metal from Aqueous Galvanic Processing Solution	MacDermid Enthone Inc.
Title  Application Filing Date Patent No. Issue Date  Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics  Process  Process  Process	Published			9/23/2016	15/762599	Flexible Color Adjustment for Dark CR (III) Platings	MacDermid Enthone Inc.
Title Application Filing Date Patent No. Issue Date	Pending			8/15/2017	15551052	Inhibitor Composition for Racks When Using Chrome Free Etches in a Plating on Plastics Process	MacDermid Enthone Inc
	Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
	POLYMERS ON DIELECTRIC SUBSTRATES (ENVISION HDI)					
MacDermid Enthone Inc.	PROCESS FOR FILLING VIAS IN THE MANUFACTURE OF MICROELECTRONICS (Anodic Pulse to Reduce Additive Build Up) [SC Cu]	15/148738	5/6/2016	10103029	10/16/2018	Granted <b>F</b>
MacDermid Enthone Inc.	AQUEOUS ELECTROLYTE COMPOSITION HAVING A REDUCED AIRBORNE	14/916706	3/4/2016	10081876	9/5/2018	Granted
	EMISSION, METHOD AND USE OF THIS COMPOSITION					
MacDermid Enthone Inc.	LEVELERS FOR COPPER DEPOSITION IN MICROELECTRONICS	14/854561	9/15/2015			Published
MacDermid Enthone Inc.	AQUEOUS STRIPPING COMPOSITION FOR METAL SURFACES	14/893854	11/24/2015	9834689	12/5/2017	Granted
MacDermid Enthone Inc.	COMPOSITIONS INCLUDING A HIGH MOLECULAR WEIGHT ACID SUITABLE FOR CONDUCTIVE POLYMER FORMATION ON DIELECTRIC SUBSTRATES	15/545208	7/20/2017			Published
MacDermid Enthone Inc.	Elimination of H2S in Immersion Tin Plating Solution	15/607925	5/30/2017			Pending
MacDermid Enthone Inc.	Textured Hardcoat Films	15/717275	9/27/2017			Pending
MacDermid Enthone Inc.	Carbon Based Direct Plating Process	15/973814	5/8/2018			Pending
MacDermid Enthone Inc.	Electrolytic Deposition of Tin/Tin-X and Plating Method	16/059086	8/9/2018			Pending
MacDermid Enthone Inc.	NEAR NEUTRAL pH PICKLE ON MULTI- METALS	15/977526	5/11/2018			Pending
MacDermid Enthone Inc. 61	Advanced Solder Alloys For Electronic Interconnects	15286759	10/6/2016			Pending
MacDermid Enthone Inc. 62	OF NON-CONDUCTING SUBSTRATES	11423474	6/12/2006			Pending

<sup>&</sup>lt;sup>61</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>62</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Pending					3030 A 10 10 10 10 10 10 10 10 10 10 10 10 10	
l Danding			9/15/2015	14776879	Electrodeposition of silver with fluoropolymer	MacDermid Enthone Inc. 72
rending			1/24/2014	14234000	metal	MacDellina Emmone me.
Danding			1/24/2014	1/22/000	Appropriate for electrochemical denocition of a	MacDamid Enthana Ina 71
Pending			2/10/2014	14001360	Aqueous solution and method for the formation	MacDermid Enthone Inc. 70
Pending			1/8/2014	13981974	Process for filling vias in the microelectronics	MacDermid Enthone Inc. 69
Pending			12/12/2012	13699910	Copper filling of through silicon vias	MacDermid Enthone Inc. 68
					containing polyaniline in a doped form and a liquid paraffin	
Pending			1/9/2013	13638442	Corrosion-protective wax composition	MacDermid Enthone Inc. 67
Pending			4/22/2011	13125622	Method for deposition of hard chrome layers	MacDermid Enthone Inc. 66
					metal layer	
Pending			6/15/2011	13003398	Electrolyte and method for deposition of matte	MacDermid Enthone Inc. 65
Pending			8/9/2010	12665908	CORROSION PROTECTION OF BRONZES	MacDermid Enthone Inc. 64
					SUBSTRATE SURFACES	
Pending			12/15/2008	12278256	METHOD AND DEVICE FOR COATING	MacDermid Enthone Inc. 63
Date Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner

<sup>64</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>63</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>67</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>66</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>65</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>68</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>69</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>70</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>71</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>72</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>74</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>73</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>76</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>75</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>78</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

77 Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>79</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>80</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>81</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

82 Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

85 Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

MacDermid Enthone Inc	MacDermid Enthone Inc. 92	MacDermid Enthone Inc. 91	MacDermid Enthone Inc. 90	MacDermid Enthone Inc. 89	MacDermid Enthone Inc. 88	MacDermid Enthone Inc. %	MacDermid Enthone Inc. 86	MacDermid Enthone Inc. 85	MacDermid Enthone Inc. 84	Owner
COPPER ELECTRODEPOSITION IN MICROELECTRONICS	CAPPING OF METAL INTERCONNECTS IN INTEGRATED CIRCUIT ELECTRONIC DEVICES	ADHESION PROMOTION IN PRINTED CIRCUIT BOARDS	Copper bath composition for electroless and/or electrolytic filling of vias and trenches for integrated circuit fabrication	Printed circuit board manufacture	Method for the deposition of a chromium alloy	Process for the non-galvanic tin plating of copper or copper alloys	Process for the extended use of electrolytes	Electroplating chemistry for the cu filling of submicron features of vlsi/ulsi interconnect	System for the electrodialytic regeneration of an electroless bath electrolyte	Title
11272999	10867346	10619198	10358596	10118417	10169959	10129998	10148090	09716975	10092976	Application No.
11/14/2005	6/14/2004	7/14/2003	2/5/2003	4/8/2002	10/3/2002	7/31/2002	10/3/2002	11/20/2000	3/7/2002	Filing Date
7303992	7268074	7232478	6897152	6860925	6837981	6821323	6797141	6776893	6723218	Patent No.
12/4/2007	9/11/2007	6/19/2007	5/24/2005	3/1/2005	1/4/2005	11/23/2004	9/28/2004	8/17/2004	4/20/2004	Issue Date
Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

<sup>84</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>85</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>86</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>87</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>89</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc. 88 Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>90</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>91</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>92</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Enthone Inc.	DEFECT REDUCTION IN	10091106	3/4/2002	7316772	1/8/2008	Granted
	ELECTRODEPOSITED COPPER FOR					
	SEMICONDUCTOR APPLICATIONS					
MacDermid Enthone Inc. 93	Cobalt and nickel electroless plating in	11085304	3/21/2005	7332193	2/19/2008	Granted
	microelectronic devices					
MacDermid Enthone Inc. 94	Capping of metal interconnects in integrated	11/852,513	9/10/2007	7393781	7/1/2008	Granted
	circuit electronic devices					
MacDermid Enthone Inc. 95	Defectivity and process control of electroless	11230912	9/20/2005	7410899	8/12/2008	Granted
	deposition in microelectronics applications					
MacDermid Enthone Inc. 96	Method for treating laser-structured plastic	11102038	4/8/2005	7578888	8/25/2009	Granted
	surfaces					
MacDermid Enthone Inc. 97	Method for etching non-conductive substrate	11554100	10/30/2006	7578947	8/25/2009	Granted
	surfaces					
MacDermid Enthone Inc. 98	Defectivity and process control of electroless	11243876	10/5/2005	7615491	11/19/2009	Granted
	deposition in microelectronics applications					
MacDermid Enthone Inc. 99	Insoluble anode	11279512	4/12/2006	7666283	2/23/2010	Granted
MacDermid Enthone Inc. 100	Copper metallization of through silicon via	12185641	8/4/2008	7670950	3/2/2010	Granted
MacDermid Enthone Inc. 101	Adhesion promotion in printed circuit boards	11759456	6/7/2007	7682432	3/23/2010	Granted

<sup>93</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>94</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>95</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>96</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>97</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>98</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>99</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>100</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Enthone Inc. 102	Manufacture of electroless cobalt deposition	11549775	6/7/2007	7704306	4/27/2010	Granted
MacDermid Enthone Inc. 103	Compositions for microelectromics applications Tin-silver solder bumping in electronics	11463355	8/9/2006	7713859	5/11/2010	Granted
	manufacture					
MacDermid Enthone Inc. 104	Organic solderability preservative comprising	11620857	1/8/2007	7794531	9/14/2010	Granted
MacDermid Enthone Inc. 105	Direct metallization of electrically non-	11756048	5/31/2007	7815785	10/19/2010	Granted
	conductive polyimide substrate surfaces					
MacDermid Enthone Inc. 106	Copper electrodeposition in microelectronics	11846385	8/28/2007	7815786	10/19/2010	Granted
MacDermid Enthone Inc.	Method for supplying a plating composition	11420339	5/25/2006	7846316	12/7/2010	Granted
	operation					
MacDermid Enthone Inc. 107	Process and electrolytes for deposition of metal	10678601	10/3/2003	7846503	12/7/2010	Granted
	layers					
MacDermid Enthone Inc. 108	Metallic surface enhancement	11736647	4/18/2007	7883738	2/8/2011	Granted
MacDermid Enthone Inc. 109	Copper deposition for filling features in	12446176	4/17/2009	7968455	6/28/2011	Granted
	manufacture of microelectronic devices					
MacDermid Enthone Inc. 110	Anti-tarnish coatings	11944287	11/21/2007	7972655	7/5/2011	Granted

<sup>102</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>103</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>104</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>106</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>105</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>107</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>108</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>109</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Очнег	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Enthone Inc. 111	Surface preparation process for damascene	12238139	9/25/2008	7998859	8/16/2011	Granted
	copper deposition					
MacDermid Enthone Inc. 112	Copper electrodeposition in microelectronics	10963369	10/12/2004	8002962	8/23/2011	Granted
MacDermid Enthone Inc. 113	Maintenance of metallization baths	11039088	1/19/2005	8057678	11/15/2011	Granted
MacDermid Enthone Inc. 114	ADHESION PROMOTION IN PRINTED	11759624	6/7/2007	8142840	3/27/2012	Granted
	CIRCUIT BOARDS					
MacDermid Enthone Inc. 115	ELECTROLYTE AND PROCESS FOR	12168680	7/7/2008	8192607	6/5/2012	Granted
	DEPOSITING A MATT METAL LAYER					
MacDermid Enthone Inc. 116	METHOD FOR REMOVING IMPURITIES	11563335	11/27/206	8202431	6/19/2012	Granted
	FROM A METAL DEPOSITION PROCESS					
	SOLUTION					
MacDermid Enthone Inc. 117	SELF ASSEMBLED MOLECULES ON	12268144	11/10/2008	8216645	7/10/2012	Granted
	IMMERSION SILVER COATINGS					
MacDermid Enthone Inc. 118	COMPOSITE COATINGS FOR WHISKER	12254207	10/20/2008	8226807	7/24/2012	Granted
	REDUCTION					
MacDermid Enthone Inc. 119	GALVANIC BATH AND PROCESS FOR	12617202	11/12/2009	8282806	10/9/2012	Granted
	DEPOSITING ZINC-BASED LAYERS					

<sup>111</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>113</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc. <sup>112</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>115</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>116</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>118</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

PATENT
REEL: 049823 FRAME: 0082

Омпет	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Enthone Inc. 120	SILVER PLATING IN ELECTRONICS MANUFACTURE	10902398	7/29/2004	8349393	1/8/2013	Granted
MacDermid Enthone Inc. 121	DEPOSITION OF CONDUCTIVE POLYMER AND METALLIZATION OF NON-CONDUCTIVE SUBSTRATES	12440355	3/25/2009	8366901	2/5/2013	Granted
MacDermid Enthone Inc. 122	Method and composition for electrodeposition of copper in microelectronics with dipyridylbased levelers	12324335	11/26/2008	8388824	3/5/2013	Granted
MacDermid Enthone Inc. 123	Electrolyte Composition and Method for the Deposition of a Zinc-Nickel Alloy Layer on a Cast Iron Or Steel Substrate	11778011	7/13/2007	8435398	5/7/2013	Granted
MacDermid Enthone Inc. 124	Copper electrodeposition in microelectronics	13/214,525	8/22/2011	8608933	12/17/2013	Granted
MacDermid Enthone Inc. 125	Anti-tarnish coatings	13/176,411	7/5/2011	8703243	4/22/2014	Granted
MacDermid Enthone Inc. 126 MacDermid Enthone Inc. 127	Metallic surface enhancement  Method and composition for electrodeposition	12596559 13/785,946	2/2/2010 3/5/2013	8741390 8771495	6/3/2014 7/8/2014	Granted Granted
MacDermid Enthone Inc. ***	Method and composition for electrodeposition of copper in microelectronicswith dipyridyl-based levelers	13//83,946	3/5/2013	8//1495	//8/2014	Granted
MacDermid Enthone Inc. 128	Cyanide free electrolyte composition for the galvanic deposition of a copper layer	13054048	4/18/2011	8808525	8/19/2014	Granted

<sup>120</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>121</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>123</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc. <sup>122</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>124</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>125</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>126</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>127</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

Date

Status

013

Granted

2014

Granted

Granted

Granted

FATENT

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MacDermid Enthone Inc. 137 ELI BA CO	MacDermid Enthone Inc. 136 CY CO DE	MacDermid Enthone Inc. 135 IMI	MacDermid Enthone Inc. <sup>134</sup> SOI SIL BO	MacDermid Enthone Inc. 133 Adl	MacDermid Enthone Inc. 132 CH SUI	MacDermid Enthone Inc. 131 Silv		MacDermid Enthone Inc. 129 Cor	Owner
ELECTROLYTIC DEPOSITION OF METAL-BASED COMPOSITE COATINGS COMPRISING NANO-PARTICLES	CYANIDE-FREE ELECTROLYTE COMPOSITION, AND METHOD FOR THE DEPOSITION OF SILVER OR SILVER ALLOY LAYERS ON SUBSTRATES	IMMERSION TIN SILVER PLATING IN ELECTRONICS MANUFACTURE	SOLDERABILITY ENHANCEMENT BY SILVER IMMERSION PRINTED CIRCUIT BOARD MANUFACTURE	Adhesion promotion in printed circuit boards	CHROMIUM-FREE PICKLE FOR PLASTIC SURFACES	Silver plating in electronics manufacture	Method for the deposition of a metal layer comprising a beta-amino acid	Composite coatings for whisker reduction	Title
12747681	12445049	12607375	10099936	13/431,560	12672980	13/735,779	13382131	13/556,522	Application No.
7/19/2010	10/13/2009	10/28/2009	3/13/2002	3/27/2012	8/12/2010	1/7/2013	3/7/2012	7/24/2012	Filing Date
9217205	9212427	9175400	9072203	9040117	9023228	8986434	8962070	8906217	Patent No.
12/22/2015	12/15/2015	11/3/2015	6/30/2015	5/26/2015	5/5/2015	3/24/2015	2/24/2015	12/9/2014	Issue Date
Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

<sup>129</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>131</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc. <sup>130</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>132</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>133</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>&</sup>lt;sup>134</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>&</sup>lt;sup>135</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>136</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

Ожпет	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Enthone Inc. 138	Defect reduction in electrodeposited copper for semiconductor applications	11/971,061	1/8/2008	9222188	12/29/2015	Granted
MacDermid Enthone Inc. 139	METHOD FOR THE POST-TREATMENT OF METAL LAYERS	13129300	7/25/2011	9222189	12/29/2015	Granted
MacDermid Enthone Inc. 140	BETA-AMINO ACID COMPRISING PLATING FORMULATION	14630268	2/24/2015	9249513	2/2/2016	Granted
MacDermid Enthone Inc. 141	ADHESION PROMOTION IN PRINTED CIRCUIT BOARDS	13558019	7/25/2012	9338896	5/10/2016	Granted
MacDermid Enthone Inc. 142	COPPER ELECTRODEPOSITION IN MICROELECTRONICS	14108954	12/17/2013	9493884	11/15/2016	Granted
MacDermid Enthone Inc. 143	PROCESS FOR ELECTROLESS COPPER DEPOSITION ON LASER-DIRECT STRUCTURED SUBSTRATES	14350971	4/10/2014	9538665	1/3/2017	Granted
MacDermid Enthone Inc. 144	METHOD FOR DIRECT METALLIZATION OF NON-CONDUCTIVE SUBSTRATES	13636087	2/4/2013	9617644	4/11/2017	Granted
MacDermid Enthone Inc. 145	Cyanide-free Electrolyte Composition and Method	14962863	12/8/2015	9657402	5/23/2017	Granted
MacDermid Enthone Inc.	Selective Plating of three dimensional surfaces to produce	16201092	11/27/2018			Pending

<sup>138</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>139</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>141</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc <sup>140</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>142</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>143</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

<sup>144</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>145</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc

MacDermid Graphics Solutions, Syst LLC Flex	MacDermid Graphics Solutions, Syst LLC Flex	MacDermid Graphics Solutions, App LLC Dev	MacDermid Graphics Solutions, App LLC Dev	MacDermid Graphics Solutions, Meth LLC Plate	MacDermid Graphics Solutions, Printing LLC Surface	MacDermid Graphics Solutions, Lase LLC Mul	MacDermid Graphics Solutions, UV LLC Prin	MacDermid Graphics Solutions, UV LLC Prin	MacDermid Graphics Solutions, Proc LLC Eler	MacDermid Graphics Solutions, Proc LLC Usin	MacDermid Graphics Solutions, Printi LLC Same	MacDermid Enthone Inc. Etcl Con	MacDermid Enthone Inc. 148 Elec	MacDermid Enthone Inc. 147 Met	MacDermid Enthone Inc. 146 Self coat	Омпет
System for Thermal Development of Flexographic Printing Plates	System for Thermal Development of Flexographic Printing Plates	Apparatus and Method for Thermally Developing Flexographic Printing Sleeves	Apparatus and Method for Thermally  Developing Flexographic Printing Elements	Method of Preexposing Relief Image Printing Plate	Printing Sleeve with an Integrated Printing Surface	Laser Image Printing Plates Comprising A Multi-Layer Slip Film	UV Absorbing Support Layers & Flexographic Printing Elements Comprising Same	UV Absorbing Support Layers & Flexographic Printing Elements Comprising Same	Processless Digitally Imaged Photopolymer Elements Using Microspheres	Processless Digitally Imaged Printing Plate Using Microspheres	Printing Sleeves and Methods for Producing Same	Etching of Plastic Using Acidic Solutions Containing Trivalent Manganese	Electroplating composition Bath [Gold]	Method and Composition for electrodeposition	Self Assembled molecules on immersion siver coat	Title
11/297725	10/837107	10/811763	10/891351	10/853342	10/754297	09/507840	10/752484	09/415811	10/768799	10/105898	09/744824	15/667002	09069442	14325601	13545030	Application No.
12/8/2005	4/30/2004	3/29/2004	7/14/2004	5/25/2004	1/9/2004	2/22/2000	1/6/2004	10/11/1999	1/30/2004	3/25/2002	1/29/2001	8/2/2017	4/29/1998	7/8/2014	7/10/2012	Filing Date
7152529	7044055	6998218	7041432	7632625	6966259	6367381	RE39835	6413699	6989220	6806018	6742453		6576114	9613858	8323741	Patent No.
12/26/2006	5/16/2006	2/14/2006	5/9/2006	12/15/2009	11/22/2005	4/9/2002	9/11/2007	7/2/2002	1/24/2006	10/19/2004	6/1/2004		6/10/2003	4/4/2017	12/4/2012	Issue Date
Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Published	Granted	Granted	Granted	Status

<sup>146</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>147</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

<sup>148</sup> Appropriate documentation to be filed with the USPTO to update owner name from Enthone Inc.

	Granted	8/3/2010	7767383	8/8/2007	11/890827	Method of Pre-Exposing Relief Image Printing Plate	MacDermid Graphics Solutions, LLC
•	Granted	5/12/2009	7531285	1/17/2006	11/333022	Method of Creating a Digital Mask for Flexographic Printing Elements In Situ	MacDermid Graphics Solutions, LLC
•	Granted	1/17/2012	8098270	3/30/2009	12/413753	Method of Creating a Digital Mask for Flexographic Printing Elements In Situ	MacDermid Graphics Solutions, LLC
	Granted	6/30/2015	9069255	11/18/2009	12/620715	Carrier Sheet for a Photosensitive Printing Element	MacDermid Graphics Solutions, LLC
•	Granted	12/1/2009	7625691	11/30/2005	11/289814	Photopolymer Printing Form with Reduced Processing Time	MacDermid Graphics Solutions, LLC
•	Granted	5/24/2011	7947427	5/21/2009	12/469721	Printing Element with an Integral Printing Surface	MacDermid Graphics Solutions, LLC
•	Granted	4/10/2007	7202008	6/23/2005	11/159704	Thermal Development System and Method of Using the Same	MacDermid Graphics Solutions, LLC
	Granted	6/13/2006	7060417	11/18/2004	10/992123	Edge Cure Prevention Process	MacDermid Graphics Solutions, LLC
1	Granted	7/24/2007	7247344	11/16/2004	10/990087	Method and Apparatus for Applying Surface Treatments to Photosensitive Printing Elements During Thermal Development	MacDermid Graphics Solutions, LLC
•	Granted	12/6/2011	8071269	11/20/2007	11/986074	Compressible Flexographic Printing Plate Construction	MacDermid Graphics Solutions, LLC
•	Granted	1/15/2008	7318994	10/14/2004	10/965315	Compressible Flexographic Printing Plate Construction	MacDermid Graphics Solutions, LLC
	Granted	6/19/2007	7232649	5/23/2006	11/439026	Method for Thermally Processing Photosensitive Printing Sleeves	MacDermid Graphics Solutions, LLC
·	Granted	7/25/2006	7081331	11/12/2004	10/987624	Method for Thermally Processing Photosensitive Printing Sleeves	MacDermid Graphics Solutions, LLC
	Granted	7/3/2007	7237482	2/10/2005	11/055196	Flexo Processor	MacDermid Graphics Solutions, LLC
	Granted	2/20/2007	7179583	10/29/2004	10/977049	Edge Cure Prevention Composition and Process for Using the Same	MacDermid Graphics Solutions, LLC
TEN	Granted	10/24/2006	7125650	7/20/2004	10/894979	Method for Bump Exposing Relief Image Printing Plates	MacDermid Graphics Solutions, LLC
	Granted	6/6/2006	7055429	4/23/2004	10/830560	Edge Cure Prevention Process	MacDermid Graphics Solutions, LLC
E- 00	Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Омист

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Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Graphics Solutions, LLC	Method and Apparatus for Thermal Processing of Photosensitive Printing Elements	12/183461	7/31/2008	8739701	6/3/2014	Granted
MacDermid Graphics Solutions, LLC	Means for Attaching a Printing Plate to a Printing Cylinder	12/367650	2/9/2009	8833258	9/16/2014	Granted
MacDermid Graphics Solutions, LLC	Method for Improving Print Performance in Flexographic Printing Plates	15/638878	6/30/2017			Published
MacDermid Graphics Solutions, LLC	Method for Improving Print Performance in Flexographic Printing Plates	12/660451	2/26/2010	9720326	8/1/2017	Granted
MacDermid Graphics Solutions, LLC	Method for Improving Print Performance in Flexographic Printing Plates	12/571523	10/1/2009	8158331	4/17/2012	Granted
MacDermid Graphics Solutions, LLC	Method for Improving Print Performance in Flexographic Printing Plates	13/411762	3/5/2012	8470517	6/25/2013	Granted
MacDermid Graphics Solutions, LLC	Method of Producing a Relief Image from a Liquid Photopolymer Resin	12/794238	6/4/2010	8476000	7/2/2013	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	12/984699	1/5/2011	8492074	7/23/2013	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	14/315883	6/26/2014	9298092	3/29/2016	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	12/826773	6/30/2010	8795950	8/5/2014	Granted
MacDermid Graphics Solutions, LLC	Photosensitive Resin Laminate and Thermal Processing of the Same	14/136547	12/20/2013	9086630	7/21/2015	Granted
MacDermid Graphics Solutions, LLC	Photosensitive Resin Laminate and Thermal Processing of the Same	13/030810	2/18/2011	8652761	2/18/2014	Granted
MacDermid Graphics Solutions, LLC	Slip Film for Relief Image Printing Element	13/169296	6/27/2011	8771926	7/8/2014	Granted
MacDermid Graphics Solutions, LLC	Method of Controlling Surface Roughness of a Flexographic Printing Plate	14/081200	11/15/2013	9291891	3/22/2016	Granted
MacDermid Graphics Solutions, LLC	Method of Controlling Surface Roughness of a Flexographic Printing Plate	13/182533	7/14/2011	8632958	1/21/2014	Granted
MacDermid Graphics Solutions, LLC	Laminated Flexographic Printing Sleeves and Methods of Making the Same	13/205107	8/8/2011	8871431	10/28/2014	Granted
MacDermid Graphics Solutions, LLC	Improved Laminating Apparatus and Method of Using the Same	13/355769	1/23/2012	8697337	4/15/2014	Granted
MacDermid Graphics Solutions, LLC	Photosensitive Resin Laminate and Thermal Processing of the Same	14/016443	9/3/2013	9223218	12/29/2015	Granted

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Graphics Solutions, LLC	Photosensitive Resin Laminate and Thermal Processing of the Same	13/091466	4/21/2011	8551688	10/8/2013	Granted
MacDermid Graphics Solutions, LLC	Methods for Improving Print Performance of Flexographic Printing Elements	13/183558	7/15/2011	8669041	3/11/2014	Granted <b>F</b>
MacDermid Graphics Solutions, LLC	Integrated Membrane Lamination and UV Exposure System and Method of Using the Same	13/372060	2/13/2012	8524442	9/3/2013	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	14/302512	6/12/2014	9046778	6/2/2015	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	13/595473	8/27/2012	8790864	7/29/2014	Granted
MacDermid Graphics Solutions, LLC	Clean Flexographic Printing Plate and Method of Making the Same	13/409374	3/1/2012	9114601	8/25/2015	Granted
MacDermid Graphics Solutions, LLC	Liquid Platemaking with Laser Engraving	13/467325	5/9/2012	9096090	8/4/2015	Granted
MacDermid Graphics Solutions, LLC	Liquid Platemaking Process	13/477556	5/22/2012	8735049	5/27/2014	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Surface Cure in Digital Flexographic Printing Plates	14/328857	7/11/2014	9329480	5/3/2016	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Surface Cure in Digital Flexographic Printing Plates	15/086402	3/31/2016	9751353	9/5/2017	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Surface Cure in Digital Flexographic Printing Plates	13/591375	8/22/2012	8808968	8/19/2014	Granted
MacDermid Graphics Solutions, LLC	Method of Improving Print Performance in Flexographic Printing Plates	13/892406	5/13/2013	9040226	5/26/2015	Granted
MacDermid Graphics Solutions, LLC	Apparatus for Thermal Processing of Flexographic Printing Elements	13/965537	8/13/2013	9649786	5/16/2017	Granted
MacDermid Graphics Solutions, LLC	Photosensitive Resin Composition	14/160799	1/22/2014	10025183	7/17/2018	Granted
MacDermid Graphics Solutions, LLC	Clean Flexographic Printing Plates and Method of Making the Same	14/458659	8/13/2014	9217928	12/22/2015	Granted
MacDermid Graphics Solutions, LLC	Method for Creating Surface Texture on Flexographic Printing Elements	14/183948	2/19/2014	9256129	2/9/2016	Granted
MacDermid Graphics Solutions, LLC	Flexographic Printing Plate with Improved Cure Efficiency	14/539171	11/12/2014	9740099	8/22/2017	Granted

mid Graphics Solutions,	MacDermid Graphics Solutions, LASER IN LLC 150	MacDermid Graphics Solutions, Laser image LLC 149	MacDermid Graphics Solutions, Flexographic Pri LLC Storage Stability	MacDermid Graphics Solutions, Method of LLC Liquid Ph	MacDermid Graphics Solutions, Improved Me LLC Printing Plate	MacDermid Graphics Solutions, LLC Flexograpi Dots	MacDermid Graphics Solutions, Method of LLC Flexograpions  Output  Dots	MacDermid Graphics Solutions, Method ar LLC Flexograp	MacDermid Graphics Solutions, Method ar LLC Flexograp	MacDermid Graphics Solutions, Customizable Pri LLC Making the Same	MacDermid Graphics Solutions, Method of LLC Flexograp	MacDermid Graphics Solutions, Carrier Sh LLC	MacDermid Graphics Solutions, Method of LLC	Очист
LASER IMAGED PRINTING PLATES	LASER IMAGED PRINTING PLATES	Laser imaged printing plates	Flexographic Printing Plate with Improved Storage Stability	Method of Producing a Relief Image from a Liquid Photopolymer Resin	Improved Method of Making a Flexographic Printing Plate	Method of Improving Light Stability of Flexographic Printing Plates Featuring Flat Top Dots	Method of Improving Light Stability of Flexographic Printing Plates Featuring Flat Top Dots	Method and Apparatus for Producing Liquid Flexographic Printing Plates	Method and Apparatus for Producing Liquid Flexographic Printing Plates	Customizable Printing Plates and Method of Making the Same	Method of Creating Hybrid Printing Dots in a Flexographic Printing Plate	Carrier Sheet and Method of Using the Same	Method of Making Relief Image Printing Plates	Title
10153946	09921589	09898152	15/590068	15/484314	15/498844	15/485504	15/067622	14/935963	15/493498	15/040617	14/829163	14/830833	14/693062	Application No.
5/23/2002	8/3/2001	7/3/2001	5/9/2017	4/11/2017	4/27/2017	4/12/2017	3/11/2016	11/9/2015	4/21/2017	2/10/2016	8/18/2015	8/20/2015	4/22/2015	Filing Date
6605410	6756181	6916596					10108087	9740103	10139730	9925757	9678429	9757919	9703201	Patent No.
8/12/2003	6/29/2004	7/12/2005					10/23/2018	8/22/2017	11/27/2018	3/27/2018	6/13/2017	9/12/2017	7/11/2017	Issue Date
Granted	Granted	Granted	Pending	Published	Pending	Published	Granted	Granted	Granted	Granted	Granted	Granted	Granted	Status

<sup>&</sup>lt;sup>149</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>151</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>&</sup>lt;sup>150</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

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					Flexographic Printing Elements	LLC
Pending			12/31/2015	14985638	Method for Creating Surface Texture on	MacDermid Graphics Solutions,
Pending			8/1/2016	15224979	Method of Making a Flexographic Printing Plate	MacDermid Graphics Solutions, LLC <sup>159</sup>
Pending			3/20/2017	15463341	Method of Improving Print Performance in Flexographic Printing Plates	MacDermid Graphics Solutions, LLC <sup>158</sup>
Pending			3/20/2017	15463379	Method of Improving Print Performance in Flexographic Printing Plates	MacDermid Graphics Solutions, LLC <sup>157</sup>
Pending			5/30/2017	15608210	Laser Imaged Printing Plates	MacDermid Graphics Solutions, LLC <sup>156</sup>
Granted	11/6/2001	6312872	10/12/1999	09417043	COMPOSITE RELIEF IMAGE PRINTING PLATES	MacDermid Graphics Solutions, LLC <sup>155</sup>
Granted	7/23/2002	6423472	3/24/2000	09535353	AQUEOUS DEVELOPABLE PHOTOSENSITIVE POLYURETHANE- METHACRYLATE	MacDermid Graphics Solutions, LLC <sup>154</sup>
Granted TEN	10/19/2004	6806018	3/25/2002	10105898	PROCESSLESS DIGITALLY IMAGED PRINTING PLATE USING MICROSPHERES	MacDermid Graphics Solutions, LLC <sup>153</sup>
Granted	1/24/2006	6989220	1/30/2004	10/768,799	Processless digitally imaged photopolymer elements using microspheres	MacDermid Graphics Solutions, LLC <sup>152</sup>
Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Owner

153 Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC 152 Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>154</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

155 Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>157</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC 156 Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>158</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

MacDermid Graphics Solutions, LLC 160 MacDermid Graphics Solutions, LLC 161 MacDermid Graphics Solutions, LLC 162 MacDermid Graphics Solutions, LLC 162 LLC 163	Apparatus for Thermal Processing of Flexographic Printing Elements Laminating Apparatus and Method of Using the Same Loading/Unloading System for Printing Plates Biodegradable Film for Flexographic Printing Plate Manufacture and Method of Using the Same	Application No. 14937267 14191529 13653916 12939388	Filing Date 11/10/2015 2/27/2014 10/17/2012 11/4/2010	Patent No.	Issue Date
MacDermid Graphics Solutions, LLC <sup>163</sup>	Biodegradable Film for Flexographic Printing Plate Manufacture and Method of Using the Same	12939388	11/4/2010		
MacDermid Graphics Solutions, LLC <sup>164</sup>	Method of Controlling Surface Roughness of a Flexographic Printing Plate	12348981	1/6/2009		
MacDermid Graphics Solutions, LLC <sup>165</sup>	Apparatus and Method for Thermally  Developing Flexographic Printing Elements	12267642	11/10/2008		
MacDermid Graphics Solutions, LLC <sup>166</sup>	Apparatus for thermal processing of Flexographic Printing	15485336	4/12/2017		
MacDermid Graphics Solutions, LLC	Method and Apparatus for Producing Liquid Flexographic Printing Plates	15493498	4/21/2017	10139730	11/27/2018
MacDermid Graphics Solutions, LLC	Slip Film for Relief Image Printing Element	13169296	6/27/2011	8771926	7/8/2014
MacDermid Graphics Solutions, LLC	Photosensitive Resin Laminate and Thermal Processing of the Same	13030810	2/18/2011	8652761	2/18/2014
MacDermid Graphics Solutions, LLC	Method of Controlling Surface Roughness of a Flexographic Printing Plate	13182533	7/14/2011	8632958	1/21/2014

<sup>161</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC <sup>160</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>162</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>163</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>164</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

<sup>165</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

Owner	Title	Application No.	Filing Date	Patent No.	Issue Date	Status
MacDermid Graphics Solutions, LLC	SLIP FILM COMPOSITIONS CONTAINING LAYERED SILICATES	10946937	9/22/2004	7736836	6/15/2010	Granted
MacDermid Graphics Solutions, LLC	METHOD FOR BUMP EXPOSING RELIEF IMAGE PRINTING PLATES	10894979	7/20/2004	7125650	10/24/2006	Granted <b>F</b>
MacDermid Graphics Solutions, LLC	APPARATUS AND METHOD FOR THERMALLY DEVELOPING FI FXOGR APHIC PRINTING SI FEVES	10811763	3/29/2004	6998218	2/14/2006	Granted
MacDermid Graphics Solutions, LLC	PROCESSLESS DIGITALLY IMAGED PHOTOPOLYMER ELEMENTS USING	10768799	1/30/2004	6989220	1/24/2006	Granted
MacDermid Graphics Solutions, LLC <sup>167</sup>	Method of Making Relief Image Printing Elements	15145230	5/3/2016	100336956	7/31/2018	Granted
MacDermid Graphics Solutions, LLC	Method of Making a Flexographic Printing Plate	15224979	8/1/2016			Pending
MacDermid Offshore Solutions, LLC	Hydraulic Fluid Compositions	14/017786	9/4/2013	8809241	8/19/2014	Granted
MacDermid Offshore Solutions, LLC	Hydraulic Fluid Compositions	13/044613	3/10/2011	8563484	10/22/2013	Granted
MacDermid Offshore Solutions, LLC	Thermally Stable Subsea Control Hydraulic Fluid Compositions	14/157928	1/17/2014	9458408	10/4/2016	Granted
MacDermid Offshore Solutions, LLC	Thermally Stable Subsea Control Hydraulic Fluid Compositions	12/173284	7/15/2008	8759265	6/24/2014	Granted
MacDermid Offshore Solutions, LLC	Environmental Subsea Control Hydraulic Fluid Compositions	12/549579	8/28/2009	8575077	11/5/2013	Granted
MacDermid Offshore Solutions, LLC	Thermally Stable Subsea Control Hydraulic Fluid Compositions	12/469337	5/20/2009	8633141	1/21/2014	Granted
MacDermid Offshore Solutions, LLC	Thermally Stable Subsea Control Hydraulic Fluid Compositions	14/041669	9/30/2013	9096812	8/4/2015	Granted
MacDermid Offshore Solutions, LLC	Composition for Removing Scale Deposits	13/475030	5/18/2012	9145508	9/29/2015	Granted
MacDermid Offshore Solutions, LLC	Environmental subsea control hydraulic fluid compositions	12549579	8/28/2009	8575077	11/5/2013	Granted

<sup>167</sup> Appropriate documentation to be filed with the USPTO to update owner name from MacDermid Printing Solutions, LLC

	Granted	4/22/2003	6551756	7/24/2000	09/624104	Solvent-Developable Printing Formulations with Improved Processing Characteristics	Napp Systems, Inc.
	Granted	7/17/2001	6262825	8/24/1999	09/382214	Apparatus & Method For The Enhanced Imagewise Exposure of a Photosensitive Material	Napp Systems, Inc.
	Granted	8/24/2004	6780566	3/11/2003	10/386315	High Performance Photoimageable Resin Composition & Printing Plates Prepared Therefrom	Napp Systems, Inc.
	Granted	6/17/2003	6579664	3/30/2001	09/823904	High Performance, Photoimageable Resin Composition & Printing Plates Prepared Therefrom	Napp Systems, Inc.
	Granted	3/17/2015	8980068	8/18/2010	12/858887	Nickel pH Adjustment Method and Apparatus	MacDermid, Incorporated/Chemtech Systems (co-owned)
	Granted	3/7/2013	5733599	9/14/2012	90/012,575	Re-Examination of Ferrier 5,733,599 (MacDermid) METHOD FOR ENHANCING THE SOLDERABILITY OF A SURFACE	MacDermid, Incorporated
	Granted	4/8/2003	6544397	3/29/2001	09/821205	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	9/3/2002	6444109	10/26/2000	09/698370	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	9/11/2007	7267259	6/6/2003	10/456329	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	12/23/2014	RE45297	2/13/2012	13/371848	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
PEEI	Granted	6/14/2005	6905587	1/14/2003	10/341859	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	3/13/2001	6200451	2/17/1999	09/251641	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	2/9/2016	RE45881	5/3/2012	13/463110	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
TEN	Granted	1/12/2016	RE45842	5/3/2012	13/463087	Method for Enhancing the Solderability of a Surface	MacDermid, Incorporated
	Granted	10/4/2016	9458408	1/17/2014	14157928	Thermally stable subsea control hydraulic fluid compositions	MacDermid Offshore Solutions, LLC
IE: nnc	Status	Issue Date	Patent No.	Filing Date	Application No.	Title	Омпет

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**RECORDED: 02/05/2019** 

Highly Reflective Substrates for the Digital   10/462977   6/16/2003   7005232   2/28/2006   Imaging of Photopolymer Printing Plates   Highly Reflective Substrates for the Digital   11/267435   11/4/2005   7083896   8/1/2006   High Performance Water-Rased Primer   10/805760   3/22/2004   7217756   5/15/2007	High Performance Water-Based Primer 10/805769 3/22/2004 7217756 5/15/2007	Napp Systems, Inc.  Napp Systems, Inc.  Napp Systems, Inc.  Napp Systems, Inc.	Highly Reflective Substrates for the Digital Imaging of Photopolymer Printing Plates Highly Reflective Substrates for the Digital Imaging of Photopolymer Printing Plates High Performance Water-Based Primer Apparatus for the Rapid Development of Photosensitive Printing Elements Flexo Cushion	10/462977 11/267435 11/805769 10/970881	6/16/2003 11/4/2005 3/22/2004 10/22/2004	7005232 7083896 7217756 7156630	2/28/2006 8/1/2006 5/15/2007 1/2/2007	Granted Granted Granted Granted Granted
وه د د د د د د د د د د د د د د د د د د د	Highly Reflective Substrates for the Digital Imaging of Photopolymer Printing Plates Highly Reflective Substrates for the Digital Imaging of Photopolymer Printing Plates Imaging of Photopolymer Printing Plates	Owner	Title	Application	Filing Date	Patent No.	Issue Date	
THE CITATION TO THE PROPERTY OF THE PROPERTY O		Napp Systems, Inc.	Apparatus for the Rapid Development of	10/970881	10/22/2004	7156630	1/2/2007	G
Apparatus for the Rapid Development of 10/970881 10/22/2004 7156630 1/2/2007	Apparatus for the Rapid Development of 10/970881 10/22/2004 7156630 1/2/2007		Photosensitive Printing Elements					
Apparatus for the Rapid Development of 10/970881 10/22/2004 7156630 1/2/2007  Photosensitive Printing Elements	Apparatus for the Rapid Development of 10/970881 10/22/2004 7156630 1/2/2007 Photosensitive Printing Elements	Napp Systems, Inc.	Flexo Cushion	12/037429	2/26/2008	8943969	2/3/2015	G